Docket No.: JCLA16667-CIP2

RECORDATION FORM (	COVER SHEET  U. S. Department of Commerce Patent and Trademark Office
PATENTS OF	NLY
To the Director of the U.S. Patent and Trademark Office: Pleas	e record the attached documents or the new address(es) below
Name of conveying party(ies) with the execution date:  GENG-SHIN SHEN, November 04, 2008  CHUN-YING LIN, November 04, 2008	2. Name/address of receiving Party(ies)  (1). ChipMOS TECHNOLOGIES INC.  NO. 1, R&D 1ST RD., SCIENCE-BASED INDUSTRIAL PARK, HSINCHU, TAIWAN, R.O.C.  (2). ChipMOS TECHNOLOGIES (BERMUDA) LTD.
3. Nature of conveyance:   x Assignment Security Agreement Change of Name Reassignment Other  4. Application number(s) or patent number(s):	CANNON'S COURT,  22 VICTORIA STREET,  HAMILTON HM12, Bermuda  Add'1 names of receiving parties  Attached? Yes X No
A. Patent Application No. (s)  12/270,602	B. Patent No.(s)
Additional number attached?  5. Name and address of party to whom correspondence concerning document should be mailed:  J. C. Patents 4 Venture, Suite 250 Irvine, CA 92618 (949) 660-0761  Atty Docket No.: JCLA16667-CIP2  9. Statement and Signature:	Yes x No  6. Total No. of applications and patents involved:  ONE (1)  7. Total fee(37CFR§3.41): \$ 40.00  Authorized to be charged by credit card  x Authorized to be charge to deposit account  Enclosed  None required (government interest not affecting title)  8. Payment Information  a. Credit Card Last 4 Numbers  Expiration Date  b. Deposit Account Number 50-0710  Authorized User Name Jiawei Huang
	lief, the forging information is true and true copy of the original document.  Total number of pages including cover sheet, attachments, and documents: 3

**PATENT** 

REEL: 021835 FRAME: 0334

ID-200809002-a 16667-US-PA-0P2

#### ASSIGNMENT

WHEREAS, 1. Shen, Geng-Shin

2. Lin, Chun-Ying

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

#### Title: MANUFACTURING PROCESS FOR A CHIP PACKAGE STRUCTURE

[] Filed:

Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, 1. ChipMOS Technologies Inc.

- of No. 1, R&D 1st Rd., Science-Based Industrial Park Hsinchu, Taiwan, R.O.C.
  - 2. ChipMOS Technologies (Bermuda) Ltd.
- of Canon's Court, 22 Victoria Street, Hamilton HM12, Bermuda

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

Second Joint Inventor (if any): Lin, Chun-Ying

ID-200809002-a 16667-US-PA-0P2

# **ASSIGNMENT CONTINUED**

indicated.					
	Gary-		Elven deng-Shin	Date:	Na/4/08
Signature:	lain	Chun	Yiua	Data:	>008/WH

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s)

# J.C. PATENTS

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## **CERTIFICATE OF TRANSMISSION**

### **November 13, 2008**

Atty Docket No.	:	JCLA16667-CIP2
Appl. No.	:	12/270,602
Filing Date	:	November, 13, 2008
Pages	:	Cover + 3

## BY FACSIMILE ONLY

Fax No.	:	571-273-0140
Attention	:	MAIL STOP Assignment Commissioner for Patents
From	:	Jiawei Huang, Reg. No. 43,330
MESSAGE	:	Enclosed herewith is a Recordation Cover Sheet with Assignment in 3 pages.

Sir:

I hereby certify that this correspondence is being facsimile transmitted to the Patent and Trademark Office on November 13, 2008 at the above indicated fax number.

Sign by

Michelle Chang

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> PATENT **REEL: 021835 FRAME: 0337**

**RECORDED: 11/13/2008**